

ABSTRACT OF THE DISCLOSURE

The invention relates to wafer processing apparatus having a chamber with an upper wall with gas supply openings formed therein which promote more even processing of a wafer. According to one embodiment of the invention, the openings are formed so as to create a circular flow path in the chamber. Another embodiment of the invention provides for the formation of the openings to create turbulent flow. A further embodiment of the invention provides for a nonuniform distribution of the openings so as to counteract a tendency for a flow over a wafer in one area to be higher than in another area.